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Thomas, M.E.; Smith, D.M.; Wallace, S.; Iwamoto, N.;
Interconnect Technology Conference, 2002. Proceedings of the IEEE 2002 International , 2002
Page(s): 223 -225

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Babcock, J.A.; Francis, P.; Bashir, R.; Kabir, A.E.; Schroder, D.K.; Lee, M.S.; Dhayagude, T.; Yindeepol, W.; Prasad, S.J.; Kalnitsky, A.; Thomas, M.E.; Hagan, Egan, K.; Bergemont, A.; Jansen, P.;
IEEE Electron Device Letters , Volume: 21 Issue: 6 , Jun 2000
Page(s): 283 -285

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Barnes, N.P.; Thomas, M.E.; Koch, G.J.; Marsh, W.B.;
Quantum Electronics, IEEE Journal of , Volume: 31 Issue: 5 , May 1995
Page(s): 962 -969

[\[Abstract\]](#) [\[PDF Full-Text \(712 KB\)\]](#) **IEEE JNL****4 Design Of Manufacturing Strategy With Wafer Cost Estimation**

Saadat, I.A.; Thomas, M.E.; Gattiker, A.; Maly, W.;
Semiconductor Manufacturing, 1994. Extended Abstracts of ISSM '94. 1994 International Symposium on , 21-22 Jun 1994
Page(s): 57 -60

[\[Abstract\]](#) [\[PDF Full-Text \(452 KB\)\]](#) **IEEE CNF****5 Are there any alternatives to "known good die" ? [M**

Gattiker, A.E.; Maly, W.; Thomas, M.E.;

Multi-Chip Module Conference, 1994. MCMC-94, Proceedings., 1994 IEEE , 1
1994
Page(s): 102 -107

[\[Abstract\]](#) [\[PDF Full-Text \(540 KB\)\]](#) **IEEE CNF**

6 Extraction of defect size distributions in an IC layer using test structure data

Khare, J.B.; Maly, W.; Thomas, M.E.;

Semiconductor Manufacturing, IEEE Transactions on , Volume: 7 Issue: 3 , A
Page(s): 354 -368

[\[Abstract\]](#) [\[PDF Full-Text \(1360 KB\)\]](#) **IEEE JNL**

7 Smart-substrate multichip-module systems

Maly, W.; Feltham, D.B.I.; Gattiker, A.E.; Hobaugh, M.D.; Backus, K.; Thom

Design & Test of Computers, IEEE , Volume: 11 Issue: 2 , Summer 1994

Page(s): 64 -73

[\[Abstract\]](#) [\[PDF Full-Text \(836 KB\)\]](#) **IEEE JNL**

8 Extraction of defect characteristics for yield estimation using the d bridge test structure

Khare, J.B.; Daniels, B.J.; Campbell, D.M.; Thomas, M.E.; Maly, W.;

VLSI Technology, Systems, and Applications, 1991. Proceedings of Technical
1991 International Symposium on , 22-24 May 1991

Page(s): 428 -432

[\[Abstract\]](#) [\[PDF Full-Text \(452 KB\)\]](#) **IEEE CNF**

9 Multilevel microcoaxial interconnect: a novel technology for VLSI microwave circuits

Thomas, M.E.; Saadat, I.A.; Sekigahama, S.;

VLSI Multilevel Interconnection Conference, 1991, Proceedings., Eighth Inter
IEEE , 11-12 Jun 1991

Page(s): 116 -122

[\[Abstract\]](#) [\[PDF Full-Text \(768 KB\)\]](#) **IEEE CNF**

10 VLSI multilevel micro-coaxial interconnects for high speed device:

Thomas, M.E.; Saadat, I.A.; Sekigahama, S.;

Electron Devices Meeting, 1990. Technical Digest., International , 9-12 Dec 1990
Page(s): 55 -58

[\[Abstract\]](#) [\[PDF Full-Text \(304 KB\)\]](#) **IEEE CNF**

11 Issues associated with the use of electroless copper films for submicron multilevel interconnections

Thomas, M.E.; Sekigahama, S.; Myers, S.A.;

VLSI Multilevel Interconnection Conference, 1990. Proceedings., Seventh Int IEEE , 12-13 Jun 1990

Page(s): 335 -337

[\[Abstract\]](#) [\[PDF Full-Text \(428 KB\)\]](#) **IEEE CNF**

12 The mechanical planarization of interlevel dielectrics for multilevel interconnect applications

Thomas, M.E.; Sekigahama, S.; Renteln, P.; Pierce, J.M.;

VLSI Multilevel Interconnection Conference, 1990. Proceedings., Seventh Int IEEE , 12-13 Jun 1990

Page(s): 438 -440

[\[Abstract\]](#) [\[PDF Full-Text \(180 KB\)\]](#) **IEEE CNF**

13 Characterization of mechanical planarization processes

Renteln, P.; Thomas, M.E.; Pierce, J.M.;

VLSI Multilevel Interconnection Conference, 1990. Proceedings., Seventh Int IEEE , 12-13 Jun 1990

Page(s): 57 -63

[\[Abstract\]](#) [\[PDF Full-Text \(324 KB\)\]](#) **IEEE CNF**

14 An advanced single-level polysilicon submicrometer BiCMOS technology

Brassington, M.P.; El-Diwany, M.H.; Razouk, R.R.; Thomas, M.E.; Tuntasoo;

Electron Devices, IEEE Transactions on , Volume: 36 Issue: 4 , Apr 1989

Page(s): 712 -719

[\[Abstract\]](#) [\[PDF Full-Text \(1072 KB\)\]](#) **IEEE JNL**

15 The potential of using refractory metals and barrier layers to generate temperature interconnects

Thomas, M.E.; Hartnett, M.P.; McKay, J.E.; Kapoor, A.K.; Chinn, J.D.;

VLSI Multilevel Interconnection Conference, 1988. Proceedings., Fifth Intern. IEEE , 13-14 Jun 1988

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